Method for Reduction of Silver Biocide Plating on Metal Surfaces

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Silver ions in aqueous solutions (0.05 to 1 ppm) are used for microbial control in water systems. The silver ions remain in solution when stored in plastic containers, but the concentration rapidly decreases to non-biocidal levels when stored in metal containers. The silver deposits onto the surface and is reduced to non-biocidal silver metal when it contacts less noble metal surfaces, including stainless steel, titanium, and nickel-based alloys.

Five methods of treatment of contact metal surfaces to deter silver deposition and reduction are proposed:
1. High-temperature oxidation of the metal surface;
2. High-concentration silver solution pre-treatment;
3. Silver plating;
4. Teflon coat by vapor deposition (titanium only); and
5. A combination of methods (1) and (2), which proved to be the best method for the nickel-based alloy application.

The mechanism associated with surface treatments (1), (2), and (5) is thought to be the development of a less active oxide layer that deters ionic silver deposition. Mechanism (3) is an attempt to develop an equilibrium ionic silver concentration via dissolution of metallic silver. Mechanism (4) provides a non-reactive barrier to deter ionic silver plating.

Development testing has shown that ionic silver in aqueous solution was maintained at essentially the same level of addition (0.4 ppm) for up to 10 months before that test was discontinued for nickel-based alloys. Method (1) resulted in the maintenance of a biocidal level (approximately 0.05 ppm) for up to 10 months before that test was discontinued for nickel-based alloys. Methods (1) and (2) used separately were able to maintain ionic silver in aqueous solution at essentially the same level of addition (0.4 ppm) for up to 10 months before the test was discontinued for stainless steel alloys. Method (3) was only utilized for titanium alloys, and was successful at maintaining ionic silver in aqueous solution at essentially the same level of addition (0.4 ppm) for up to 10 months before the test was discontinued for simple flat geometries, but not for geometries that are difficult to Teflon coat.

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Title to this invention has been waived under the provisions of the National Aeronautics and Space Act (42 U.S.C. 2457(f)) to Hamilton Sundstrand. Inquiries concerning licenses for its commercial development should be addressed to:

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Silicon Micromachined Microlens Array for THz Antennas

There is strong demand for a multi-pixel heterodyne detector array for Earth observation, astrophysics, future planetary, and ground applications.

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A 5x5 silicon microlens array was developed using a silicon micromachining technique for a silicon-based THz antenna array. The feature of the silicon micromachining technique enables one to microfabricate an unlimited number of microlens arrays at one time with good uniformity on a silicon wafer. This technique will resolve one of the key issues in building a THz camera, which is to integrate antennas in a detector array. The conventional approach of building single-pixel receivers and stacking them to form a multi-pixel receiver is not suited at THz because a single-pixel receiver already has difficulty fitting into mass, volume, and power budgets, especially in space applications.

Photograph of Silicon Microlens Array Antenna. The reason why there are different sizes of silicon microlenses is that each column has a different diameter of microlens on the mask plate. The microlens diameter of each column is very uniform.

In this proposed technique, one has controllability on both diameter and curvature of a silicon microlens. First of all, the diameter of microlens depends on how thick photoresist one could coat and pattern. So far, the diameter of a 6-mm photoresist microlens with 400 µm in height has been successfully microfabricated. Based on current researchers’ experiences, a diameter larger than 1-cm photoresist microlens array would be feasible.

In order to control the curvature of the microlens, the following process variables could be used:
1. Amount of photoresist: It determines the curvature of the photoresist microlens. Since the photoresist lens is